ATMOSS®

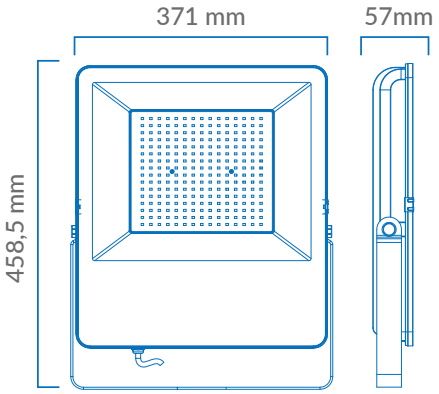
L I G H T I N G

Used
OSRAM
LED Chips

PROYECTOR EXTERIOR LED 30000LM 200W

A+

Referencia	ref.PRY-417	ref.PRY-129	ref.PRY-110
Potencia	200W	200W	200W
Color de luz	3200K	4200K	5000K
Lúmenes	30000 lm	30000 lm	30000 lm
Ángulo	120º	120º	120º
IP	IP65	IP65	IP65
Voltaje	AC 220-240V	AC 220-240V	AC 220-240V
Hercios	50/60 Hz	50/60 Hz	50/60 Hz
Clase	CLASE II	CLASE II	CLASE II
Chip	OSRAM	OSRAM	OSRAM
Factor de Potencia	FP>0.9	FP>0.9	FP>0.9
Rotación	360º	360º	360º
IK	08	08	08



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INSTRUCCIONES PROYECTOR EXTERIOR

ESPECIFICACIONES:

· POTENCIA: 200W
· RANGO DE TENSIÓN: 85-265V AC 50/60Hz
· GRADO IP: IP65
· PESO: 4.6 kg

INSTRUCCIONES GENERALES Y RECOMENDACIONES DE SEGURIDAD:

· Se recomienda evitar mirar la luz de muy cerca y en forma directa por su alta intensidad lumínica y evitar encandilamiento innecesario.

· Debe instalarse en un lugar ventilado, nunca dentro de una caja o habitáculo estanco.

· El reflector se enfría naturalmente por convección de aire.

· Este producto está preparado para resistir a la intermperie.

· Para limpieza, asegurarse de que la luminaria esté desconectada de la red eléctrica. No utilizar hidrolavadoras a la hora de su limpieza ya que si bien su grado de estanqueidad es IP65 el agua a alta presión puede dañar el sellado.

· No utilizar en recintos donde exista peligro de explosión.

· No utilizar en recintos donde se almacenen materiales inflamables.

· No instalar bajo el agua u otro tipo de líquidos.

· Cambiar el vidrio templado en caso de rotura.

· Esta unidad es fácilmente reparable, incluso en su lugar de instalación siempre por personal cualificado.

· La distancia entre el reflector y cualquier objeto debe ser de al menos 1 metro.

LIMPIEZA:

Antes de limpiar el reflector, desconectarlo de la red de alimentación y esperar hasta que el mismo se enfríe lo suficiente. Esto evita que el vidrio templado cambie bruscamente su temperatura y se dañe.

Limpiar con un paño ligeramente húmedo para remover la suciedad acumulada.

Recomendamos que la instalación sea realizada por una persona cualificada y autorizada.
Asegúrese de desconectar la corriente antes de realizar la instalación.

MANTENIMIENTO:

· Verificar la conexión, el cableado y la carcasa del reflector de LED si están dañados antes de usar.

· Sólo requiere ser limpiado con un paño cuando se note sucio, para mejorara la luminosidad.

INSTRUCCIONES DE MONTAJE EN PARED:

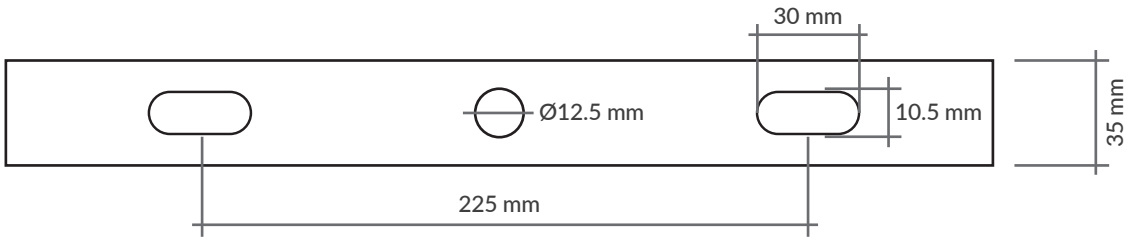
1. Debe ser instalado por personal cualificado.

2. Sólo debe ser montado sobre superficies francas, sin grietas y sin humedad.

3. Posición de montaje: La luminaria debería ser instalada mediante tarugos (tipo Fischer).

4. Marcar las posiciones de los huecos sobre la pared. Agujerear sobre las posiciones marcadas anteriormente. Atornillar sobre la pared con los tornillos adecuados.

DISTANCIA DE ANCLAJE



GWM JTLRSA.EM

DURIS® E 2835

The DURIS® E 2835 combines good efficacy and a wide beam angle into a compact format (2.8 mm x 3.5 mm). This is key to homogeneous illumination applications where the DURIS® E 2835 never fails to impress with its performance on system level.

Applications

- Downlights/Spotlights
- Lamp Retrofits

Features:

- Package: white SMT package, colored diffused silicone resin
- Typ. Radiation: 120° (Lambertian emitter)
- CRI: 70 (min.)
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM Class 2)
- Luminous Flux: min 100 lm @ typ. 2700K

Ordering Information

Type	Color temperature	Luminous Flux [1] I_F = 100 mA Φ_V	Ordering Code
GWM JTLRSA.EM-0912-2210-1	2200 K	90 ... 130 lm	Q65113A0188
GWM JTLRSA.EM-1013-2708-1	2700 K	100 ... 140 lm	Q65113A0194
GWM JTLRSA.EM-1014-3007-1	3000 K	100 ... 150 lm	Q65113A0204
GWM JTLRSA.EM-1016-4005-1	4000 K	100 ... 170 lm	Q65113A0195
GWM JTLRSA.EM-1016-5003-1	5000 K	100 ... 170 lm	Q65113A0197
GWM JTLRSA.EM-1016-5702-1	5700 K	100 ... 170 lm	Q65113A0198
GWM JTLRSA.EM-1016-6501-1	6500 K	100 ... 170 lm	Q65113A0196

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min. max.	-40 °C 105 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 105 °C
Junction Temperature	T_j	max.	125 °C
Forward Current T_A = 25 °C	I_F	max.	100 mA
Power Dissipation	P_D	max.	1000 mW
Thermal resistance	Rthj-s		20°C/W
Antistatic ability(HBM)	ESD		2 kV

Characteristics

I_F = 100 mA; T_A = 25 °C

Parameter	Symbol		Values
Viewing angle at 50% I_V	2φ	typ.	120 °
Forward Voltage [2)]	V_F	min.	8.5 V
		max.	10.0 V
Color Rendering Index [3)]	CRI	min.	70

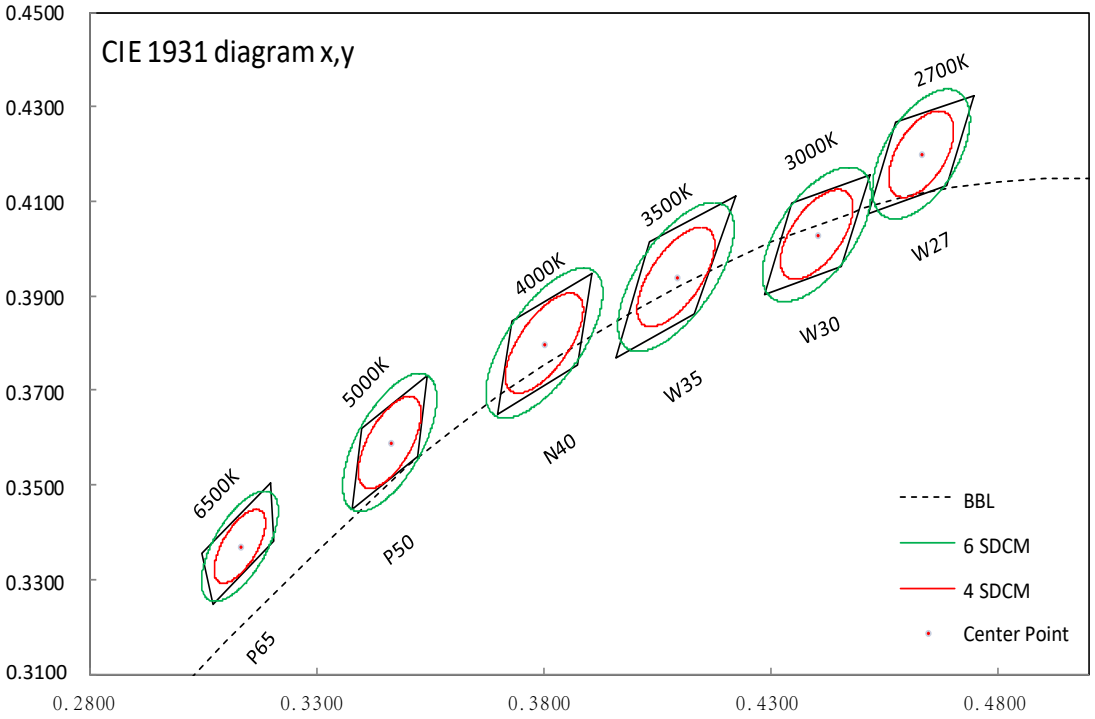
Brightness Groups

	Luminous Flux [4] I_F = 100 mA min. Φ_V	Luminous Flux [4] I_F = 100 mA max. Φ_V
10	100 lm	110 lm
11	110 lm	120 lm
12	120 lm	130 lm
13	130 lm	140 lm
14	140 lm	150 lm
15	150 lm	160 lm
16	160 lm	170 lm

Forward Voltage Groups

	Forward Voltage [2] min. V_F	Forward Voltage [2] max. V_F
85	8.5 V	9.0 V
90	9.0 V	9.5 V
95	9.5 V	10.0 V

Chromaticity Coordinate Groups [5)]



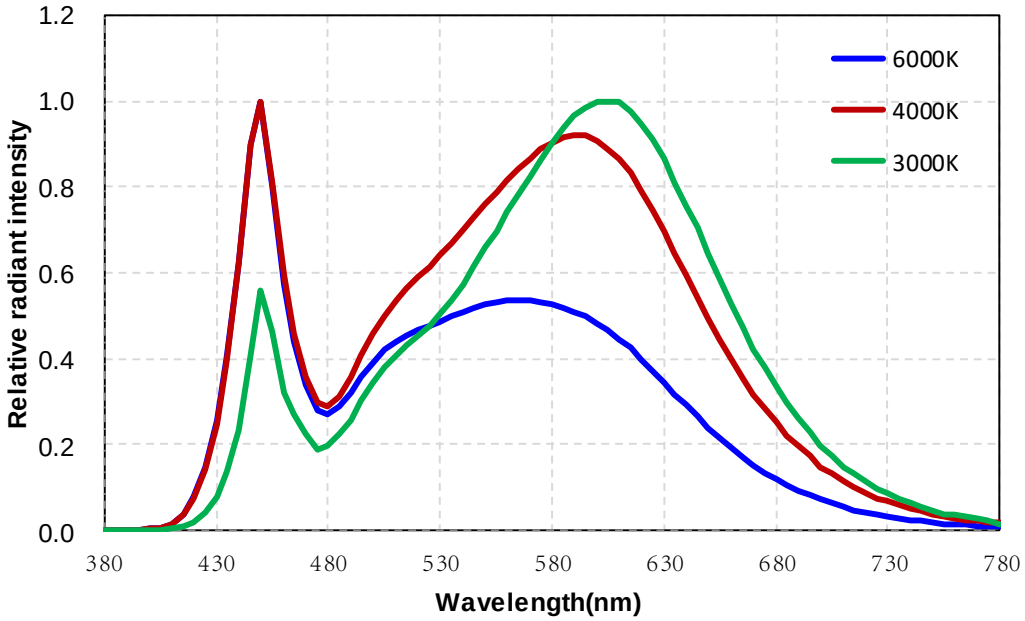
Chromaticity Coordinate Groups [5)]

TC(K)	CIE-X	CIE-Y	BIN	SDCM
2700K	0.4746	0.4325	W27	＜6
	0.4575	0.4266		
	0.4514	0.4075		
	0.4685	0.4134		
	0.4630	0.4200	Center Point	
3000K	0.4516	0.4155	W30	＜6
	0.4345	0.4096		
	0.4284	0.3904		
	0.4455	0.3964		
	0.4400	0.4030	Center Point	
3500K	0.4223	0.4112	W35	＜6
	0.4033	0.4016		
	0.3958	0.3769		
	0.4130	0.3861		
	0.4090	0.3940	Center Point	
4000K	0.3904	0.3949	N40	＜6
	0.3728	0.3848		
	0.3696	0.3651		
	0.3872	0.3752		
	0.3800	0.3800	Center Point	
5000K	0.3544	0.3731	P50	＜6
	0.3397	0.3620		
	0.3376	0.3449		
	0.3523	0.3560		
	0.3460	0.3590	Center Point	
5700K	0.3347	0.3574	P57	＜6
	0.3223	0.3454		
	0.3227	0.3276		
	0.3351	0.3396		
	0.3287	0.3425	Center Point	
6500K	0.3196	0.3503	P65	＜6
	0.3048	0.3354		
	0.3070	0.3248		
	0.3205	0.3380		
	0.313	0.337	Center Point	

Notes:
*XY tolerance is ±0.005.
*Ta = 25 °C. RH = 60%

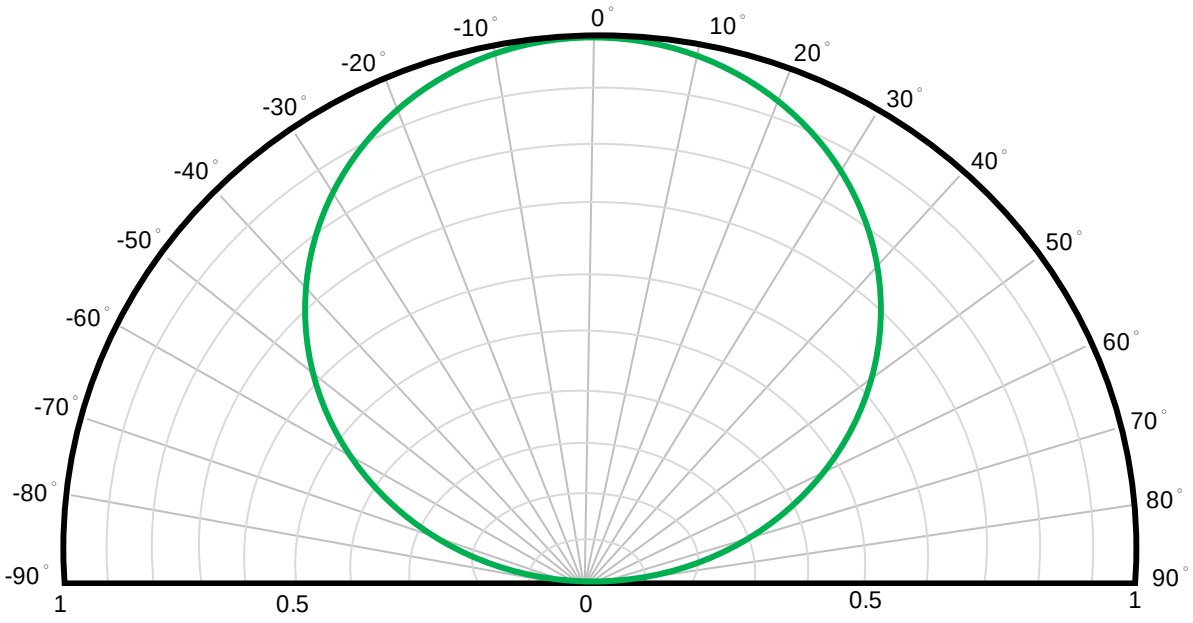
Relative Spectral Emission [6)]

$\Phi_{rel} = f(\lambda)$; $I_F = 100$ mA; $T_A = 25$ °C



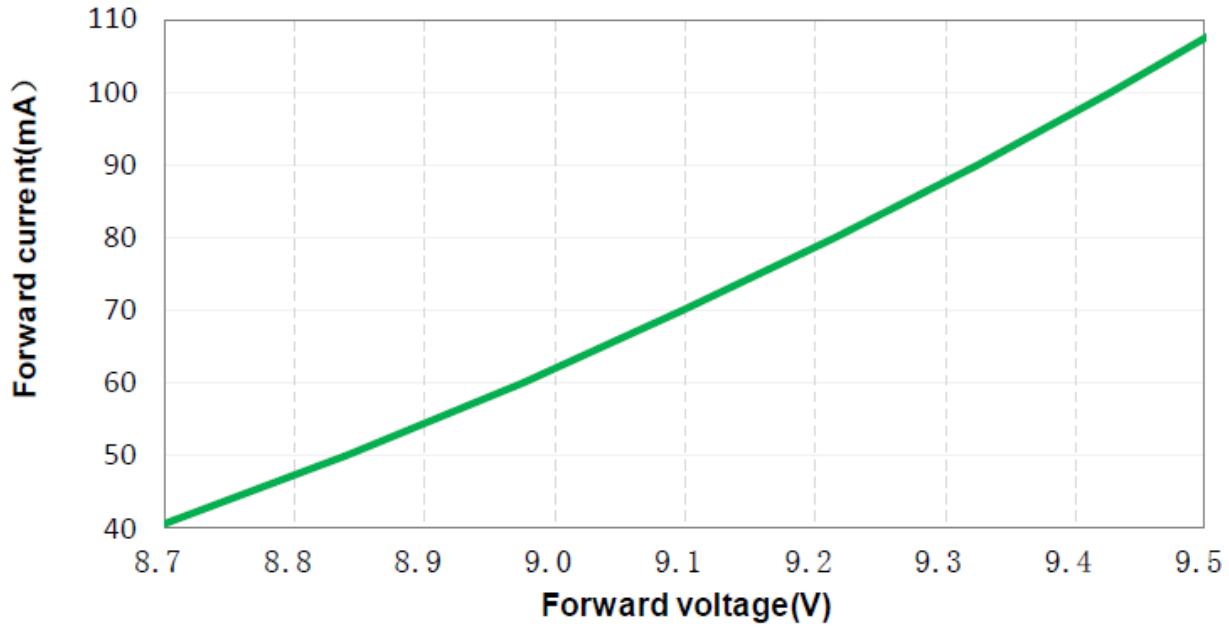
Radiation Characteristics [6)]

$I_{rel} = f(\phi)$; $T_A = 25$ °C



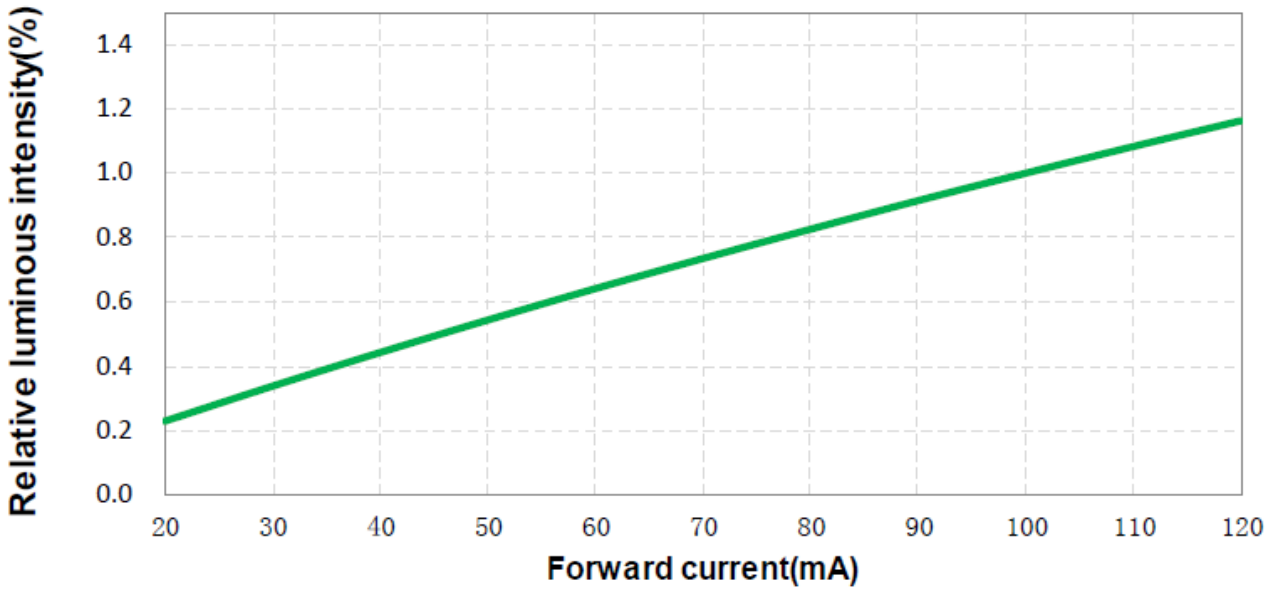
Forward current [6), 7)]

$I_F = f(V_F)$; T_A = 25 °C



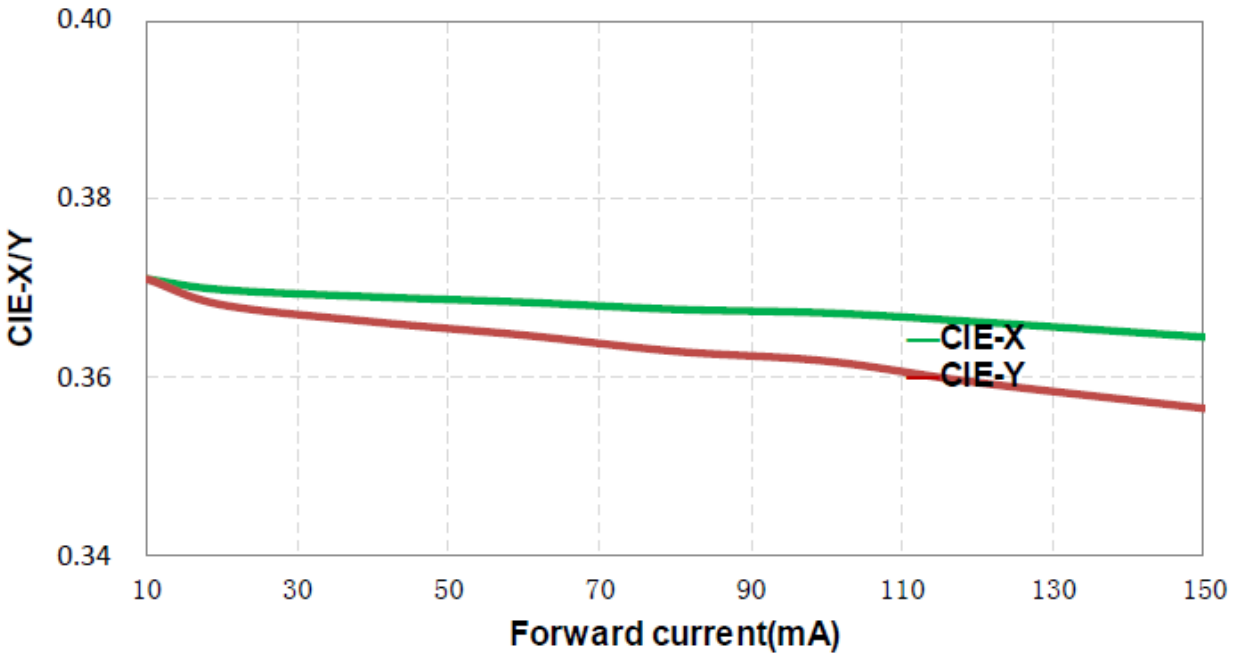
Relative Luminous Flux [6), 7)]

$\Phi_v/\Phi_v(100\ mA) = f(I_F)$; T_A = 25 °C



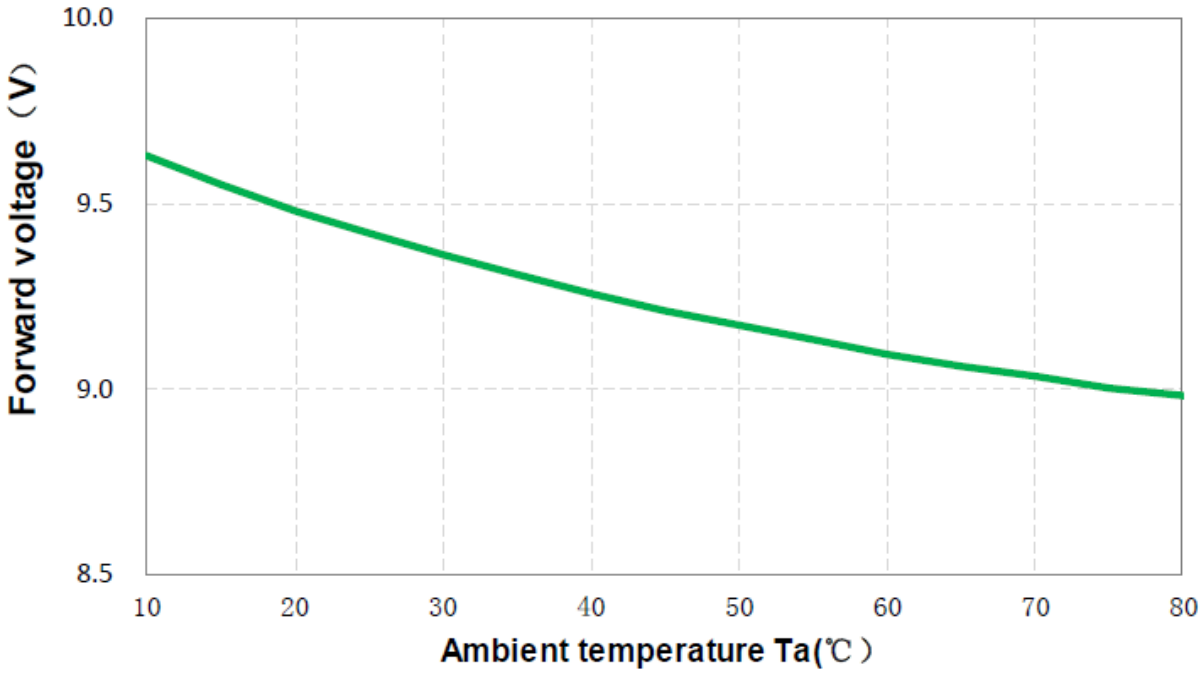
Chromaticity Coordinate Shift [6)]

$\Delta Cx, \Delta Cy = f(T_j); I_F = 100$ mA



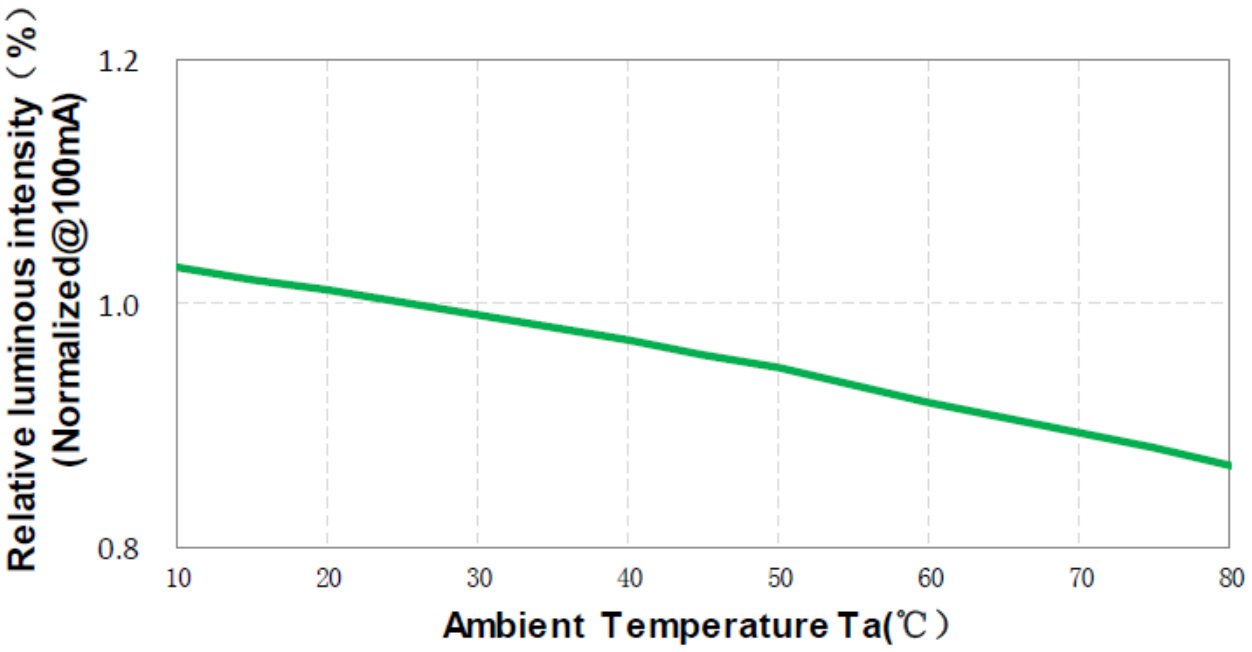
Forward Voltage [6)]

$\Delta V_F = V_F - V_F(25\ °C) = f(T_j); I_F = 100$ mA



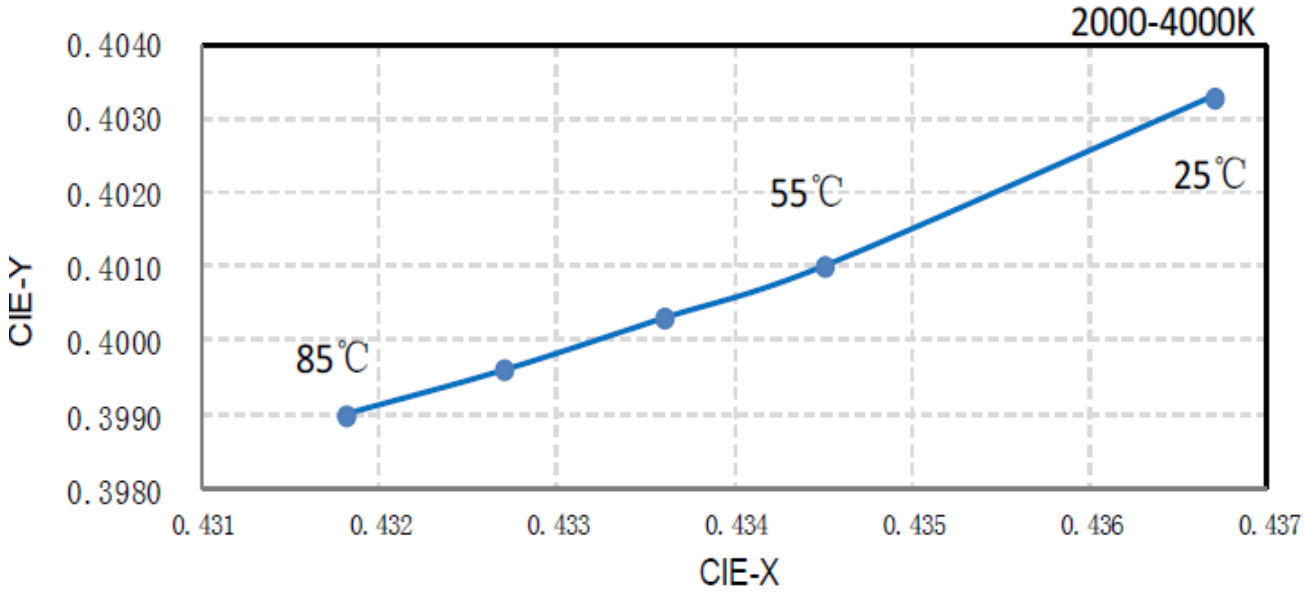
Relative Luminous Flux [6)]

$\Phi_v/\Phi_v(25\ °C) = f(T_j)$; $I_F = 100$ mA



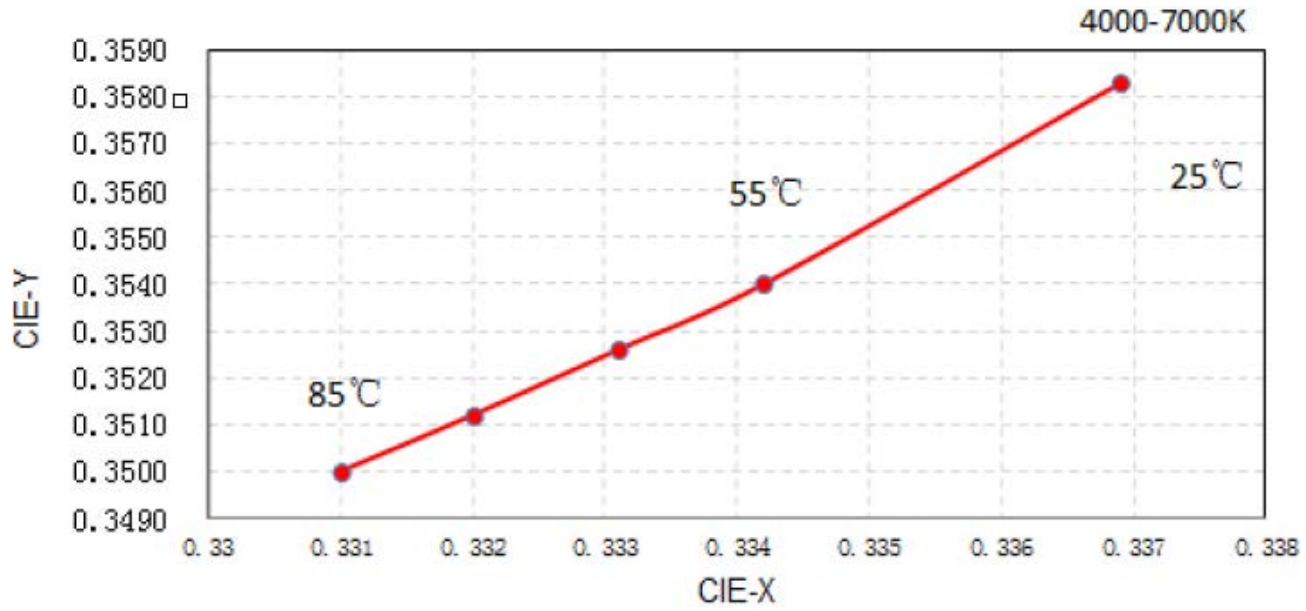
Chromaticity Coordinate Shift [6)]

$\Delta Cx, \Delta Cy = f(I_F)$; $T_J = 25\ °C$



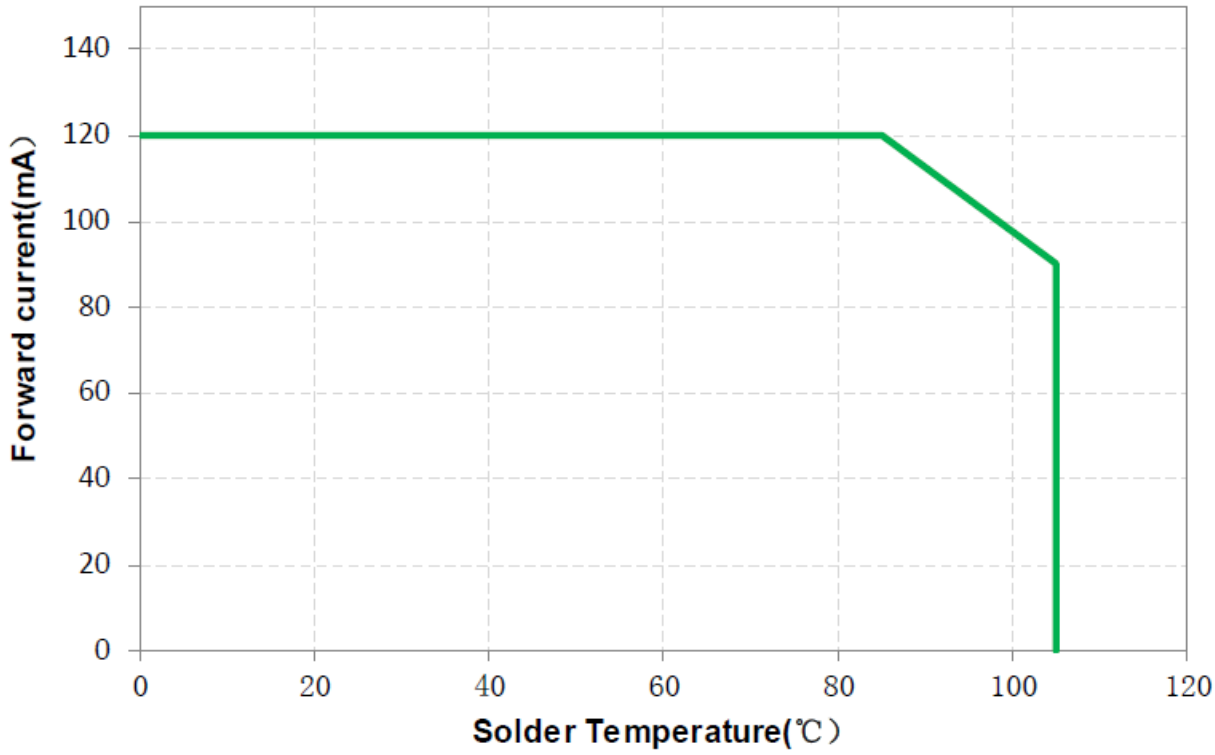
Chromaticity Coordinate Shift [6)]

$\Delta Cx, \Delta Cy = f(I_F); T_J = 25\ °C$

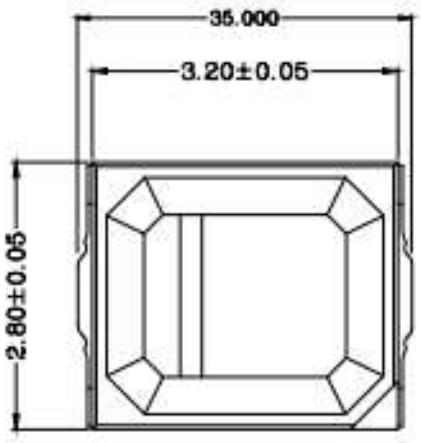


Max. Permissible Forward Current

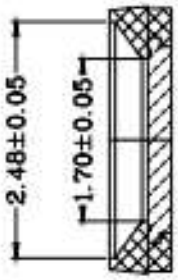
$I_F = f(T)$



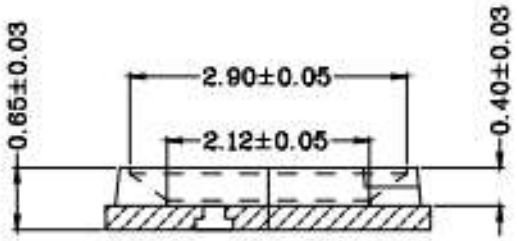
Dimensional Drawing [8)]



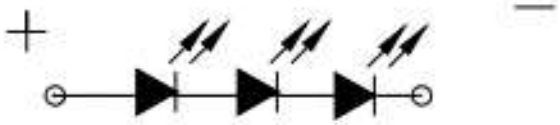
Top View

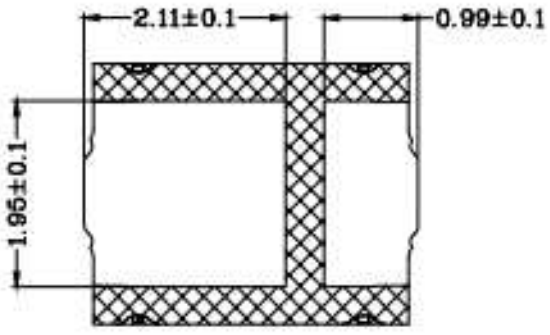


Size View

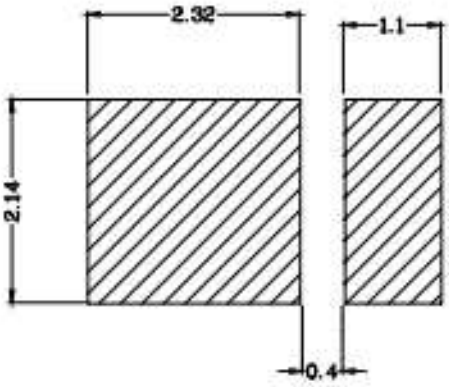


Size View



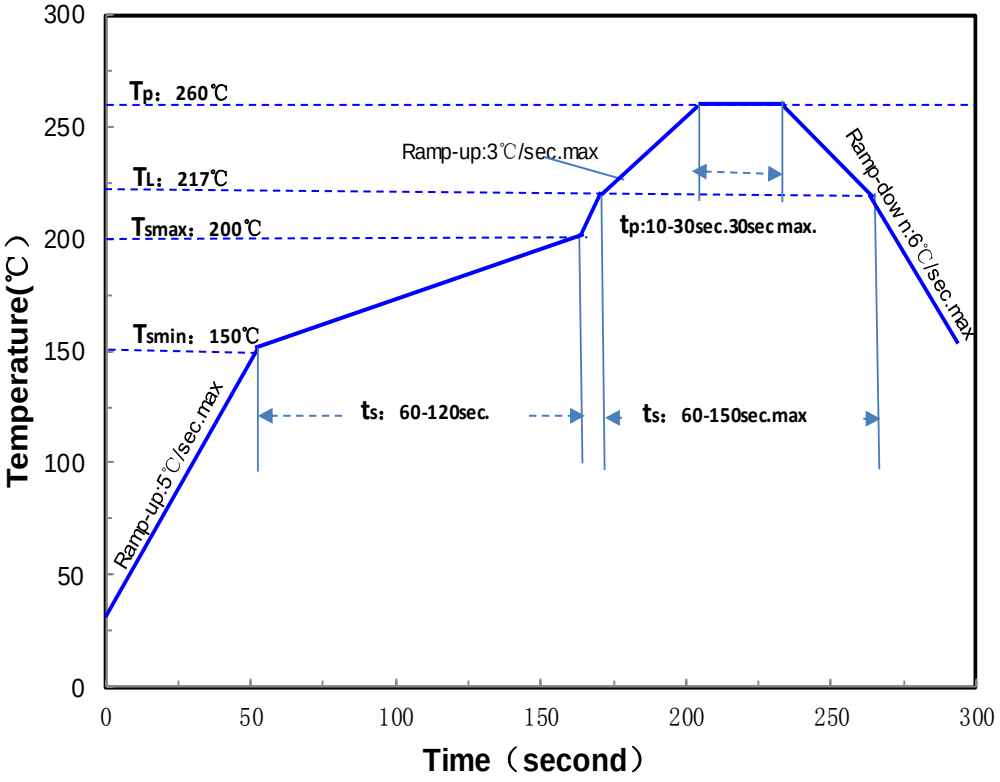


Bottow View



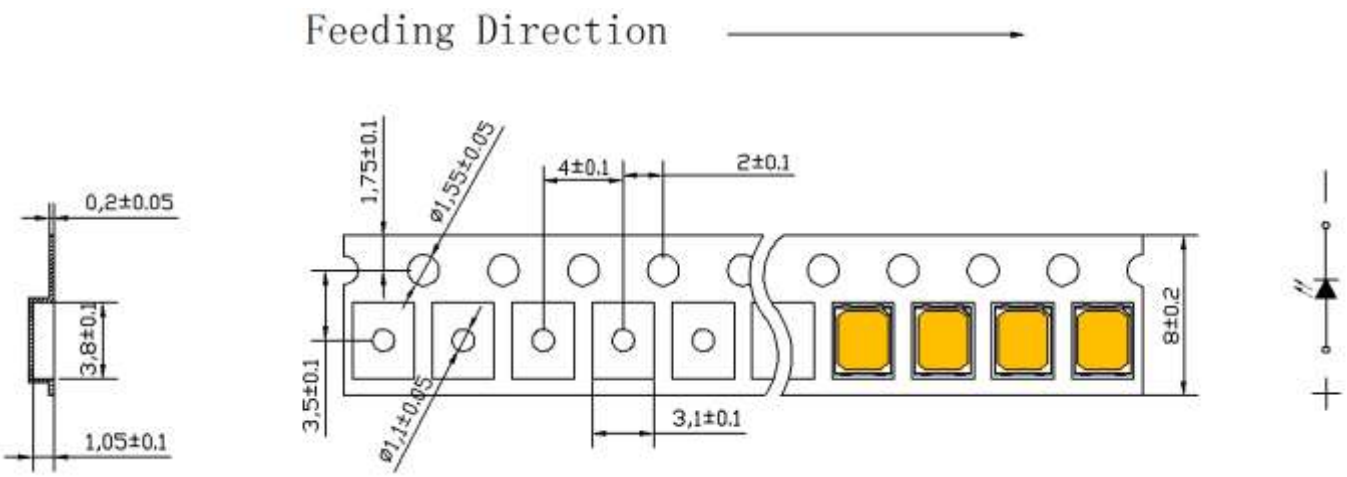
Recommended bonding pad design

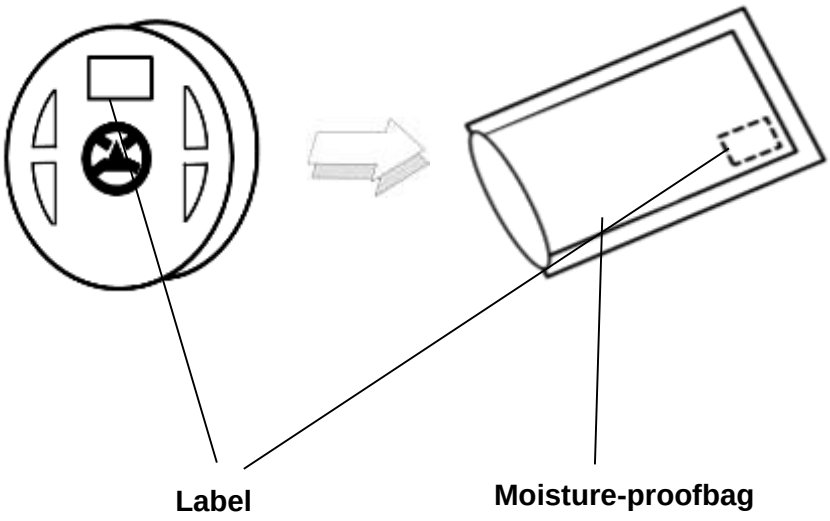
Reflow Soldering Profile



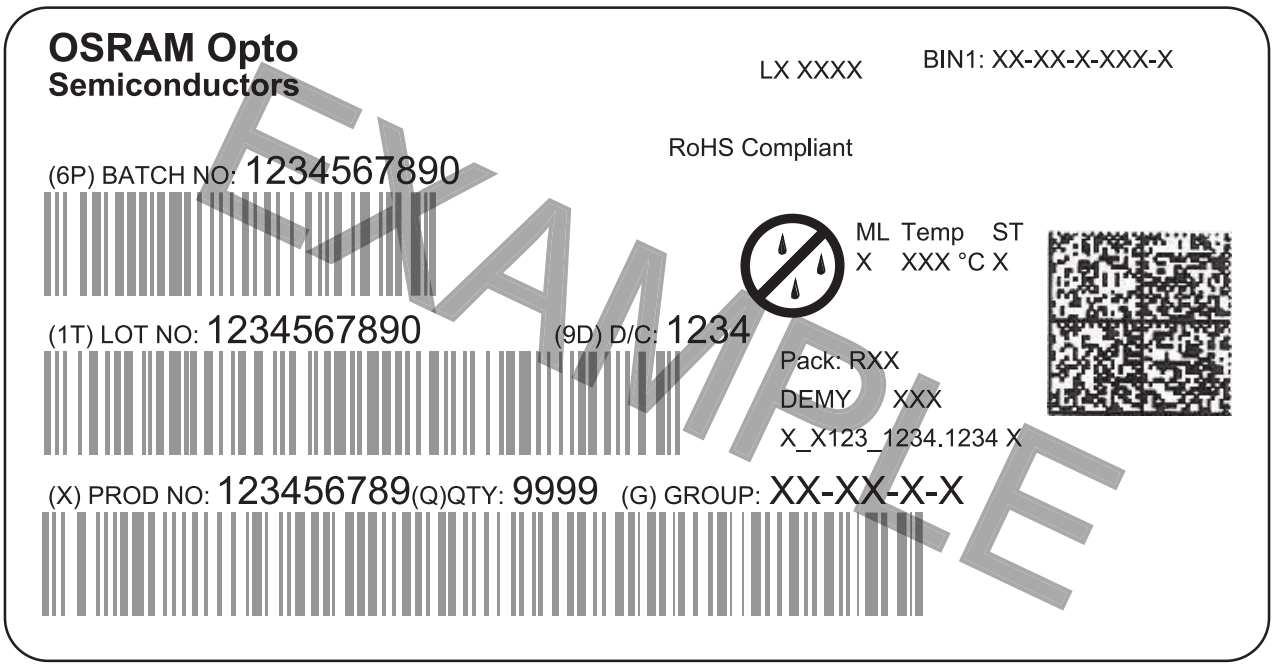
Profile Feature	Lead Free Assembly
Temperature min（T_{smin}） Temperature max(T_{smax}) Maximum time (t_s)from Tsmin to T_{smax}	150℃ 200℃ 120 seconds
Ramp-up(T_L to T_P)	3℃/sec
Liquids Temperature(T_L)	217℃
Maximum Time(t_L) Maintained T_L	150 seconds
Maximum Peak Package Body Temperature(T_p)	260℃
Time Within 5℃ of the Specified Temperature	10-30seconds
Maximum Ramp-Down Rate(T_p to T_L)	6℃/seconds
Maximum Time 25℃ to Peak Temperature	8minutes

Package information [8)]





Barcode-Product-Label (BPL)



OHA04563

Precautions

1. Repairing
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

2. Storage：

a. Don’t open the moisture proof bag before ready to use the LEDs.
b. The LEDs should be kept at 30℃ or less and 65%RH or less before opening the package. The max. period before opening the package is 1 year.
c. After opening the package, the LEDs should be kept at 30℃/60%RH or less, and it should be used within 3 days. If the LEDs should be kept at 30-60%RH or more, and it should be used within 12hours.
d. If the LEDs be kept over the conditions of 30%, baking is required before mounting. Baking condition as below: 70±5℃ for 12 hours for roll goods, 105±5℃ for 1 hours for bulk goods.
e. The environment have no acid, alkali, corrosive gas, intensively shake and high magnetic field.

3. Cautions:
The encapsulated material of the LEDs is silicone. Therefore, the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper.

2.Handling Precautions:

a. LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.
b. In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.
c. Advises against the use of any chemicals or materials that have been found or are suspected to have an adverse effect on device performance or reliability. To verify compatibility, it is recommended that all chemicals and materials be tested in the specific application and environment for which they are intended to be used.
d. Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.
e. In designing a circuit, the current through each LED must be exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen.
f. Thermal design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, color change and so on. Please consider the heat generation of the LEDs when making the system design.
g. Other points for attention, please refer to our LED user manual.

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **low risk (exposure time 100 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

This device is designed for specific/recommended applications only. Please consult OSRAM Opto Semiconductors Sales Staff in advance for detailed information on other non-recommended applications (e.g. automotive).
Change management for this component is aligned with the requirements of the lighting market.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

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Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS webside.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices

In case Buyer – or Customer supplied by Buyer– considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordi-nate the customer-specific request between OSRAM OS and Buyer and/or Customer.

Glossary

1) **Brightness:** Brightness values are measured during a current pulse of typically 10 ms, with a tolerance of +/- 7%.
2) **Reverse Operation**: Not designed for reverse operation. Continuous reverse operation can cause migration and damage of the device.
3) **Forward Voltage:** The Forward voltage is measured during a current pulse duration of typically 1 ms with a tolerance of ± 0.05V .
4) **Color reproduction index:** Color reproduction index values (CRI-RA) are measured during a current pulse of typically 10 ms and with a tolerance of ±2.
5) **Chromaticity coordinate groups:** Chromaticity coordinate groups are measured during a current pulse duration of typically 10ms with a tolerance of ±0.005.
6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.

Published by OSRAM Opto Semiconductors GmbH
Leibnizstraße 4, D-93055 Regensburg

EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，不含有毒有害物质或元素。

OSRAM
Opto Semiconductors